

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hyun Jin LEE	12/12/2011
RECEIVING PARTY DATA	
Name:	Hynix Semiconductor Inc.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13341304
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Address Line 4:	Mountlake Terrace, WASHINGTON 98043
ATTORNEY DOCKET NUMBER:	100BK-019300US
NAME OF SUBMITTER:	Steve Y. Cho
Total Attachments: 1 source=2011_12_30_ASSGMT_100BK-019300US#page1.tif	

OP \$40.00 13341304

**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

Date(s) of Execution of Declaration:

Filing Date: December 30, 2011

Application No.: 13/341,304 ; and

WHEREAS, Hynix Semiconductor Inc. of San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request AMPACC Law Group, PLLC, 6100 219<sup>th</sup> Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

December 12, 2011  
Date:

Hyunjin Lee,   
Name: Hyun Jin LEE